

MICROELECTRONIC DEVICES AND METHODS FOR PACKAGING  
MICROELECTRONIC DEVICES

ABSTRACT OF THE DISCLOSURE

Microelectronic devices and methods of packaging microelectronic devices are disclosed herein. In one embodiment, a method includes placing a plurality of singulated radiation responsive dies on a support member, electrically connecting circuitry of the radiation responsive dies to contacts of the support member, and forming a barrier on the support member between adjacent radiation responsive dies without an adhesive attaching the barrier to the support member. The barrier is formed on the support member after electrically connecting the circuitry of the dies to the contacts of the support member. The barrier can encapsulate at least a portion of the wire-bonds.